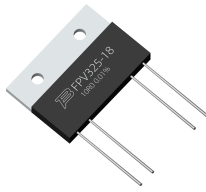


MATERIAL DECLARATION SHEET



Material Number	FPV Series			
Product Line	Fixed Resistors			
Compliance Date	2025/7/29			
RoHS Compliant	Yes	MSL	1	

Reference part number: FPV325 Series (20W)

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Lead Plating	Tin Plating	160.04	Tin	7440-31-5	96.5	2.098	2.174
				Copper	7440-50-8	0.5	0.011	
				Silver	7440-22-4	3	0.065	
2	Leads	Copper	525	Copper	7440-50-8	100	7.13	7.13
3	Inside Soldering	Plating	156	Tin	7440-31-5	96.5	2.045	2.12
				Copper	7440-50-8	0.5	0.011	
				Silver	7440-22-4	3	0.064	
4	Heatsink	Aluminium	3990	Aluminium	7429-90-5	100	54.191	54.191
5	Foildbond	M-bond	40	Epoxy	68928-70-1	100	0.543	0.543

MATERIAL DECLARATION SHEET



6	Substrate	Ceramic	321.74	Aluminum nitride	24304-00-5	100	4.37	4.37
7	Resistor Material	NiCr-Foil	45.01	Chromium	7440-47-3	20	0.122	2.225
				Nickel	7440-02-0	75	0.458	
				Aluminum	7429-90-5	2.5	0.015	
				Copper	7440-50-8	2.5	1.63	
8	Chipbond	Filled Epoxy	100	Epoxy	25068-38-6	100	1.358	1.358
9	Solder Point	Filled Epoxy	67	Epoxy	25068-38-6	100	0.91	0.91
10	Bond for Solder Point	Filled Epoxy	8	Epoxy	25068-38-6	100	0.109	0.109
11	Cover	Silicone Based	120	Silicon	7440-21-3	100	1.63	1.63
12	Mold	Epoxy	1830	Epoxy black	68928-70-1	100	24.855	24.855
			Total weight	7362.79				

This Document was updated on: 2025/7/29

MATERIAL DECLARATION SHEET



Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. Resistive material weight will be different based on the resistance value.
3. The weight of the core and coating material will differ based on the size.